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Parameter	Value	Unit
$V_{CES, \text{min}}$ @ 25 °C	650	V
Maximum junction temperature	175	°C
$I_C, \text{pulse}$	45	A

$V_{CE(\text{sat}), \text{typ}}$  @  $V_{GE}=15$  V                    1.65                    V

**Absolute Maximum Ratings** at  $T_{vj}=25$  °C unless otherwise noted

Parameter	Symbol	Value	Unit
Collector emitter voltage	$V_{CES}$	650	V
Gate emitter voltage	$V_{GES}$	$\pm 20$	V
Transient gate emitter voltage, $T_P$ $\mu$ s, D<0.01		$\pm 30$	V
Continuous collector current <sup>1)</sup> , $T_c=25$ °C	$I_c$	30	A
Continuous collector current <sup>1)</sup> , $T_c=100$ °C		15	A
Pulsed collector current <sup>2)</sup> , $T_c=25$ °C	$I_{C, \text{pulse}}$	45	A
Diode forward current <sup>1)</sup> , $T_c=25$ °C	$I_F$	30	A
Diode forward current <sup>1)</sup> , $T_c=100$ °C		15	A
Diode pulsed current <sup>2)</sup> , $T_c=25$ °C	$I_{F, \text{pulse}}$	45	A
Power dissipation <sup>3)</sup> , $T_c=25$ °C	$P_D$	250	W
Operation and storage temperature	$T_{stg}, T_{vj}$	-55 to 175	°C
Short circuit withstand time $V_{GE}=15$ V, $V_{CC}=400$ V Allowed number of short circuits<1000 Time between short circuits: 1.0 S $T_{vj}=150$ °C	$t_{sc}$	10	s

**Thermal Characteristics**

Parameter	Symbol	Value	Unit
IGBT thermal resistance, junction-case	R	0.6	°C/W
Diode thermal resistance, junction-case	R	2.0	°C/W
Thermal resistance, junction-ambient <sup>4)</sup>	R	75	°C/W

**Electrical Characteristics** at  $T_{vj}=25$  unless otherwise specified

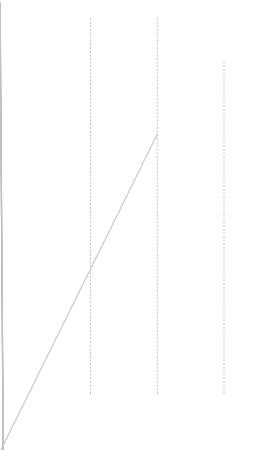
Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Collector-emitter breakdown voltage	$V_{(BR)CES}$	650			V	$V_{GE}=0$ V, $I_C=0.5$ mA
Collector-emitter saturation voltage	$V_{CE(sat)}$		1.65	2.0	V	$V_{GE}=15$ V, $I_C=15$ A, $T_{vj}=25$ °C
			1.8		V	$V_{GE}=15$ V, $I_C=15$ A, $T_{vj}=125$ °C
			1.9			$V_{GE}=15$ V, $I_C=15$ A, $T_{vj}=175$ °C
Gate-emitter threshold voltage	$V_{GE(th)}$	4.4	5.2	6.0	V	$V_{CE}=V_{GE}$ , $I_D=0.5$ mA
Diode forward voltage	$V_F$		1.8			$V_{GE}=0$ V, $I_F=15$ A, $T_{vj}=25$ °C

**Dynamic Characteristics**

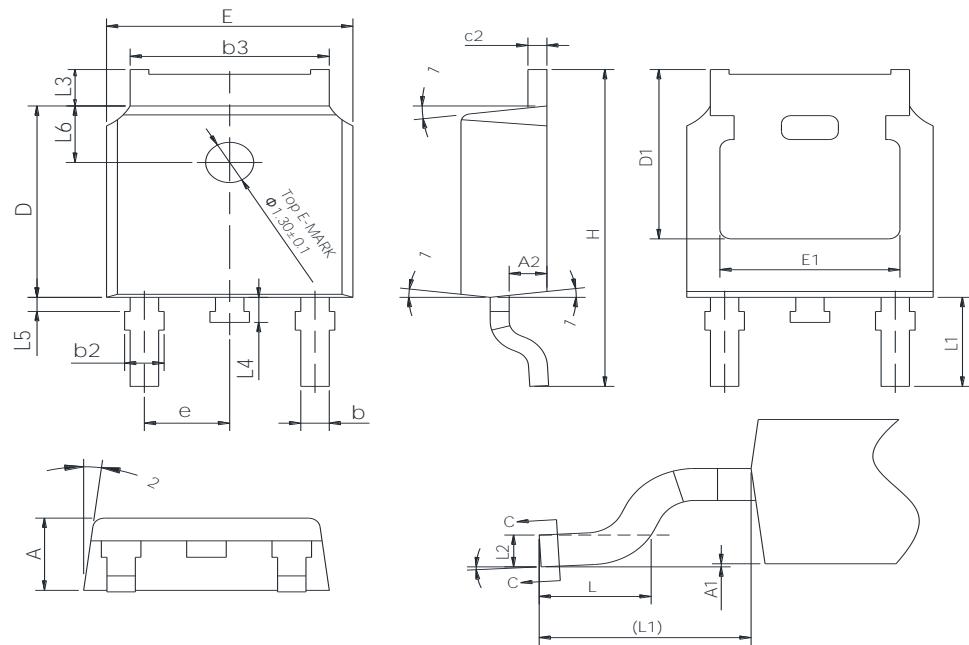
Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Input capacitance	C <sub>ies</sub>		2015		pF	V <sub>GE</sub> =0 V, V <sub>CE</sub> =25 V, 100 kHz
Output capacitance	C <sub>oes</sub>		80		pF	
Reverse transfer capacitance	C <sub>res</sub>		41		pF	
Turn-on delay time	t <sub>d(on)</sub>		50		ns	
Rise time	t <sub>r</sub>		36		ns	V <sub>GE</sub> =15 V, V <sub>cc</sub> =400 V, R <sub>g</sub> =10 I <sub>C</sub> =15 A
Turn-off delay time	t <sub>d(off)</sub>		143		ns	
Fall time	t <sub>f</sub>		94		ns	
Turn-on energy	E <sub>on</sub>		0.62	& T <sub>c</sub> 2.7600 nC/EP/3TBD2ID573634 3D19HJD(F)2G		

**Electrical Characteristics Diagrams**

<b>Figure 1. Typical output characteristics (<math>T_{vj}=25\text{ }^{\circ}\text{C}</math>)</b>	<b>Figure 2. Typical output characteristics (<math>T_{vj}=150\text{ }^{\circ}\text{C}</math>)</b>
<b>Figure 3. Typical transfer characteristics (<math>V_{CE}=20\text{ V}</math>)</b>	<b>Figure 4. Typical capacitance (<math>V_{GE}=0\text{V}, f=100\text{ kHz}</math>)</b>
<b>Figure 5. Typical gate charge</b>	<b>Figure 6. Gate-emitter threshold voltage</b>

	
<b>Figure 7. Typical collector-emitter voltage</b>	<b>Figure 8. Forward characteristic of diode</b>
<b>Figure 9. IGBT transient thermal impedance</b>	<b>Figure 10. Diode transient thermal impedance</b>

### Package Information



Symbol	mm		
	Min	Nom	Max
A	2.20	2.30	2.38
A1	0.00	-	0.10
A2	0.90	1.01	1.10
b	0.72	-	0.85
b1	0.71	0.76	0.81
b2	0.72	-	0.90
b3	5.13	5.33	5.46
c	0.47	-	0.60
c1	0.46	0.51	0.56
c2	0.47	-	0.60
D	6.00	6.10	6.20
D1	5.25	-	-
E	6.50	6.60	6.70
E1	4.70	-	-
e	2.186	2.286	2.386
H	9.80	10.10	10.40
L	1.40	1.50	1.70
L1	2.90 REF		
L2	0.508 BSC		
L3	0.90	-	1.25
L4	0.60	0.80	1.00
L5	0.15	-	0.75
L6	1.80 REF		
	0	-	

Version 1: TO252-J package outline dimension

## Ordering Information

Package Type	Units/Reel	Reels/Inner Box	Units/Inner Box	Inner Boxes/Carton Box	Units/Carton Box
TO252-J	2500	2	5000	5	25000

## Product Information

Product	Package	Pb Free	RoHS	Halogen Free
OST15N65DRF	TO252	yes	yes	yes